

# XN04501 (XN4501)

Silicon NPN epitaxial planer transistor

For general amplification

## ■ Features

- Two elements incorporated into one package.
- Reduction of the mounting area and assembly cost by one half.

## ■ Basic Part Number of Element

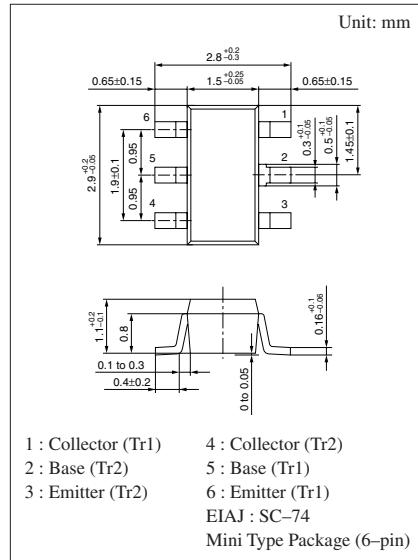
- 2SD0601A(2SD601A) × 2 elements

## ■ Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Ratings	Unit
Rating of element	Collector to base voltage	V <sub>CBO</sub>	60	V
	Collector to emitter voltage	V <sub>CEO</sub>	50	V
	Emitter to base voltage	V <sub>EBO</sub>	7	V
	Collector current	I <sub>C</sub>	100	mA
	Peak collector current	I <sub>CP</sub>	200	mA
Overall	Total power dissipation	P <sub>T</sub>	300	mW
	Junction temperature	T <sub>j</sub>	150	°C
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C

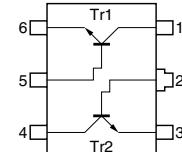
## ■ Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to base voltage	V <sub>CBO</sub>	I <sub>C</sub> = 10µA, I <sub>E</sub> = 0	60			V
Collector to emitter voltage	V <sub>CEO</sub>	I <sub>C</sub> = 2mA, I <sub>B</sub> = 0	50			V
Emitter to base voltage	V <sub>EBO</sub>	I <sub>E</sub> = 10µA, I <sub>C</sub> = 0	7			V
Collector cutoff current	I <sub>CBO</sub>	V <sub>CB</sub> = 20V, I <sub>E</sub> = 0			0.1	µA
	I <sub>CEO</sub>	V <sub>CE</sub> = 10V, I <sub>B</sub> = 0			100	µA
Forward current transfer ratio	h <sub>FE</sub>	V <sub>CE</sub> = 10V, I <sub>C</sub> = 2mA	160		460	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 100mA, I <sub>B</sub> = 10mA		0.1	0.3	V
Transition frequency	f <sub>T</sub>	V <sub>CB</sub> = 10V, I <sub>E</sub> = -2mA, f = 200MHz		150		MHz
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0, f = 1MHz		3.5		pF

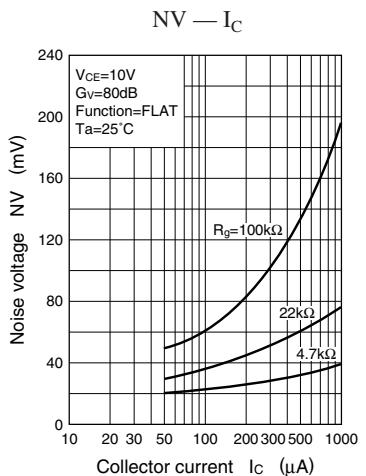
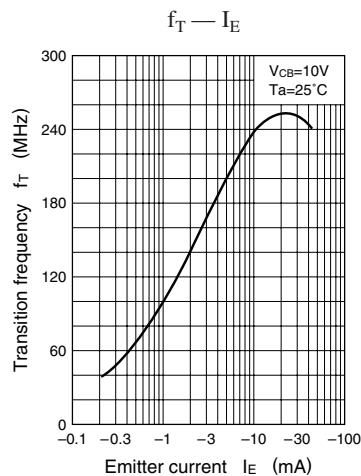
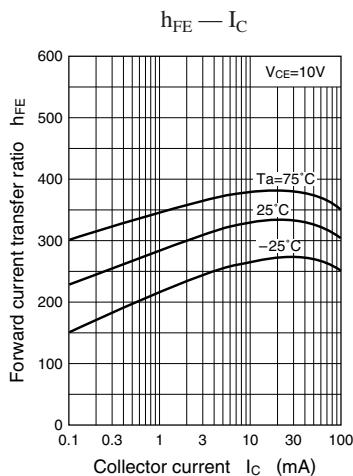
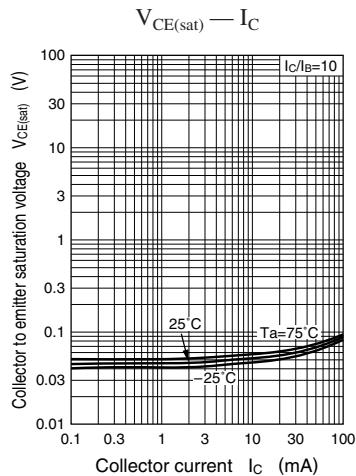
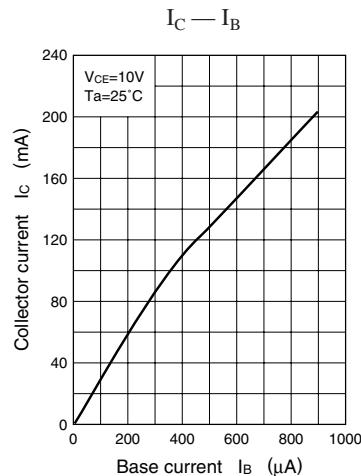
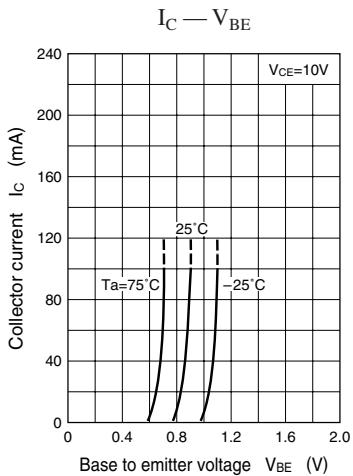
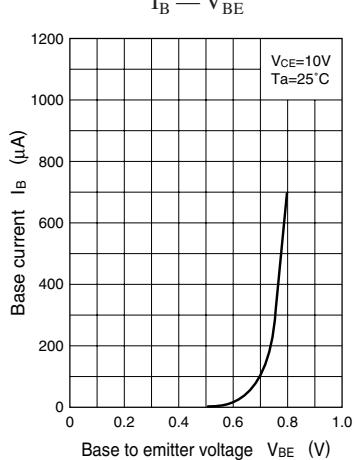
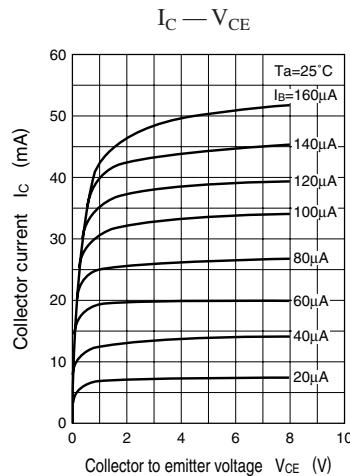
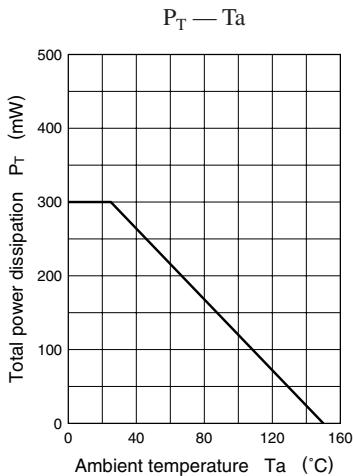


Marking Symbol: 5H

## Internal Connection



Note.) The Part number in the Parenthesis shows conventional part number.



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